



Material Content Data Sheet



Halogen-Free

Sales Product Name IAUZ40N06S5L050

Issued

23. June 2021

MA# MA005435320

Package PG-TSDSON-8-33

Weight*

36.49 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.549	1.50	1.50	15039	15039
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		85	
	non noble metal	zinc	7440-66-6	0.012	0.03		341	
	non noble metal	iron	7439-89-6	0.249	0.68		6818	
	non noble metal	copper	7440-50-8	10.102	27.69	28.41	276857	284101
wire	noble metal	gold	7440-57-5	0.026	0.07	0.07	714	714
encapsulation	organic material	carbon black	1333-86-4	0.036	0.10		993	
	plastics	epoxy resin	-	1.867	5.12		51158	
	inorganic material	silicondioxide	60676-86-0	16.220	44.46	49.68	444531	496682
leadfinish	non noble metal	tin	7440-31-5	0.400	1.10	1.10	10970	10970
plating	noble metal	silver	7440-22-4	0.086	0.23	0.23	2347	2347
solder	non noble metal	tin	7440-31-5	0.016	0.04		438	
	noble metal	silver	7440-22-4	0.020	0.05		547	
	non noble metal	lead	7439-92-1	0.763	2.09	2.18	20907	21892
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001			34	
	non noble metal	zinc	7440-66-6	0.005	0.01		138	
	non noble metal	iron	7439-89-6	0.100	0.28		2751	
	non noble metal	copper	7440-50-8	4.075	11.17	11.46	111684	114607
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			16	
	non noble metal	zinc	7440-66-6	0.002	0.01		64	
	non noble metal	iron	7439-89-6	0.047	0.13		1288	
	non noble metal	copper	7440-50-8	1.908	5.23	5.37	52280	53648
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com